AMENDMENTS TO THE CLAIMS

Claim amendments and status:

1. (Canceled)

2. (Canceled)

3. (Canceled)

4. (Canceled)

5. (Canceled)

6. (Canceled)

7. (Canceled)

8. (Canceled)

9. (Canceled)

10. (Currently Amended) The high frequency module as claimed in ~~claim 9~~ claim 14, wherein said projecting portion of the heat sink is formed from one end to the other end of the heat sink.

11. (Original) The high frequency module as claimed in claim 10, wherein the heat sink is fabricated by extruding aluminum metal.

12. (Currently Amended) The high frequency module as claimed in ~~claim 9~~ claim 14, wherein the cap has a flat portion covering the heat sink and extended portions led out from opposite edges of the flat portion.

13. (Original) The high frequency module as claimed in claim 12, wherein the extended portion of the cap is in contact with a first side surface of the substrate.

14. (Previously Presented) A high frequency module for mounting on a motherboard, comprising:

a substrate;

a semiconductor chip fixed on the substrate;

a heat sink having a projecting portion in contact with the semiconductor chip; and

a means, provided to cover the heat sink, for conducting heat transferred to the heat sink to the substrate;

wherein the heat conducting means is a cap having a flat portion covering the heat sink and extended portions led out from opposite edges of the flat portion; and

wherein the extended portions of the cap are connected to electrodes formed on the motherboard.

15. (Previously Presented) A high frequency module for mounting on a motherboard, comprising:

a substrate;

a semiconductor chip fixed on the substrate;

a heat sink having a projecting portion in contact with the semiconductor chip;

a means, provided to cover the heat sink, for conducting heat transferred to the heat sink to the substrate; and

an electronic component provided in a space formed between the heat sink and the substrate.

16. (Original) The high frequency module as claimed in claim 15, wherein the electronic component is thicker than the semiconductor chip.

17. (Previously Presented) The high frequency module as claimed in claim 13, wherein an upper surface of a non reciprocal circuit element is in contact with the flat portion of the cap.

18. (Original) The high frequency module as claimed in claim 17, wherein a first side surface of the non reciprocal circuit element is in contact with a second side surface of the substrate opposite to the first side surface of the substrate opposite to the first side surface thereof.

19. (Original) The high frequency module as claimed in claim 18, wherein the second side surface of the substrate and the first side surface of the non reciprocal circuit element have substantially the same length.

20. (Original) The high frequency module as claimed in claim 18, wherein a second side surface of the non reciprocal circuit element opposite to the first side surface thereof is in contact with the extended portion of the cap.

21. (Original) The high frequency module as claimed in claim 12, wherein the cap has bent portions led out from the other opposite edges of the flat portion.

22. (Original) The high frequency module as claimed in claim 21, wherein the bent portions are led out from the flat portion by a shorter distance than the extended portions are led out therefrom.

23. (Original) The high frequency module as claimed in claim 22, wherein the bent portions extend to points short of side surfaces of the substrate to leave openings between the ends thereof and the substrate.

24. (Canceled)

25. (Canceled)

26. (Canceled)

27. (Canceled)

28. (Canceled)